

**Assembly Transfer of Small Body Punched LFCSP Products to Amkor Philippines
AP1**

**Qualification Plan Summary of 4x4mm and 5x5mm
Hidden Paddle Punched LFCSP at Amkor Philippines**

QUALIFICATION PLAN			
TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
Temperature Cycle (TC)*	<i>JEDEC JESD22-A104</i>	3 x 77	January 2016
Unbiased Highly Accelerated Stress Test (uHAST)*	<i>JEDEC JESD22-A118</i>	3 x 77	January 2016
Solder Heat Resistance (SHR)*	<i>JEDEC/IPC J-STD-020</i>	3 x 11	January 2016
High Temperature Storage (HTS)	<i>JEDEC JESD22-A103</i>	1 x 77	January 2016
Electrostatic Discharge <i>Field Induced Charge Device Model</i>	<i>JEDEC JESD22-C101</i>	3/voltage	January 2016

*Preconditioned per JEDEC/IPC J-STD-020

**Assembly Transfer of Small Body Punched LFCSP Products to Amkor Philippines
AP1**

**Qualification Results Summary of 4x4mm and 5x5mm
Punched LFCSP at Amkor Philippines**

QUALIFICATION PLAN			
TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
Temperature Cycle (TC)*	<i>JEDEC JESD22-A104</i>	3 x 77	PASS
Unbiased Highly Accelerated Stress Test (uHAST)*	<i>JEDEC JESD22-A118</i>	3 x 77	PASS
Solder Heat Resistance (SHR)*	<i>JEDEC/IPC J-STD-020</i>	3 x 11	PASS
High Temperature Storage (HTS)	<i>JEDEC JESD22-A103</i>	1 x 77	PASS
Electrostatic Discharge <i>Field Induced Charge Device Model</i>	<i>JEDEC JESD22-C101</i>	3/voltage	PASS ±1250V

*Preconditioned per JEDEC/IPC J-STD-020